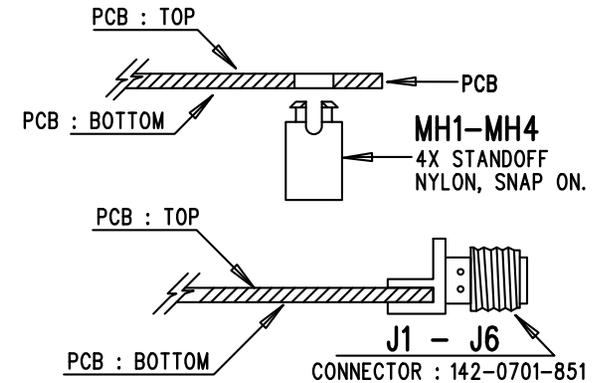


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	PRODUCTION	CLARENCE M.	03-27-13

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AND SMA CONNECTORS AS SHOWN BELOW:



8. USE BLACK PERMANENT MARKER TO WRITE THE APPROPRIATE INFORMATION ON THE WHITE BLOCK AREAS BASED ON THE TABLE BELOW:

ASSY	U1	-BIT	MSPS
DC1975A-A	LTC2270CUP	16	20

APPROVALS		LINEAR TECHNOLOGY		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY	
PCB DES.	KIM T.	TITLE: TOP ASSEMBLY DRAWING			
APP ENG.	CLARENCE M.	2-CHANNEL, HIGH SPEED LOW POWER ADC FAMILY, CMOS			
		SIZE N/A	IC NO. LTC2XXXCUP FAMILY DEMO CIRCUIT 1975A	REV. 1	
SCALE = NONE		FILENAME: DC1975A-1.PCB		SHT 1 OF 2	

